

L Number	Hits	Search Text	DB	Time stamp
1	392648	heat with (spreader radiate sink stiffener metal slug lid top cover)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:28
2	207062	((thincore coreless (thin adj core) thin) with (substrate board pc pcb pb cb (printed adj board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:33
3	139852	((semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) and (packaging package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:32
4	2882	((heat with (spreader radiate sink stiffener metal slug lid top cover)) and ((thincore coreless (thin adj core) thin) with (substrate board pc pcb pb cb (printed adj board)))) and ((semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) and (packaging package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:34
5	222398	((thincore coreless (thin adj core) thin) with (substrate board pc pcb pb cb carrier (printed adj board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:34
6	3128	((heat with (spreader radiate sink stiffener metal slug lid top cover)) and ((thincore coreless (thin adj core) thin) with (substrate board pc pcb pb cb carrier (printed adj board)))) and ((semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) and (packaging package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:34
7	2053	((heat with (spreader radiate sink stiffener metal slug lid top cover)) and ((thincore coreless (thin adj core) thin) with (substrate board pc pcb pb cb carrier (printed adj board)))) and ((semiconductor flipchip (flip adj chip) ic (integrated adj circuit)) and (packaging package))) and (Pga pin pins bga ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/29 19:35